

SMB1N-375V

- UV High Power LED
- 375 nm, 560 mW
- Integrated ESD Protection
- AllnGaN chip, 1000 x 1000 μm
- Beam Angle: ± 65°



Description



SMB1N-375V is a surface mount AllnGaN based high power ultraviolet LED, with a typical peak wavelength of 375 nm, optical output power of 560 mW @ 500 mA, and **integrated ESD protection**. It comes in polyamide resin SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and silicone resin mold. Additional variants with different beam angles are available on request.

Maximum Ratings*

Parameter	Symbol	Va	Unit				
raiailletei	Symbol	Min.	Max.	Onit			
Power Dissipation	PD		2200	mW			
Forward Current	lF		500	mA			
Pulse Forward Current **	I FP		700	mA			
Reverse Voltage	U R	not designed for reverse operation					
Reverse Current (U _R = 5V)	I_R						
Thermal Resistance	RTHJA		10	K/W			
Junction Temperature	T_J		120	°C			
Operating Temperature	TCASE	- 40	+ 100	°C			
Storage Temperature	T _{STG}	- 40	+ 100	°C			
Lead Solder Temperature (t _{max} . 5s)	T _{SLD}		+ 250	°C			

^{*}Operating close to or exceeding these parameters may damage the device

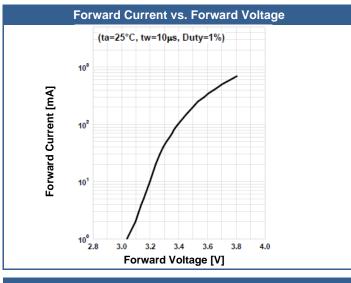
Electro-Optical Characteristics (TCASE = 25°C)

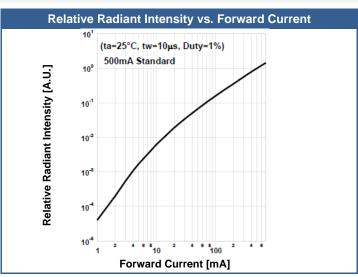
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	λ_P	I _F =500 mA	370		380	nm
Half Width	λ_{Δ}	I _F =500 mA		11		nm
Forward Voltage	UF	I _F =500 mA		3.7	4.5	V
	UFP	I _{FP} =700 mA*		3.8		
Total Radiated Power	Po	$I_F=500 \text{ mA}$		560		mW
		I _{FP} =700 mA*		800		
Radiant Intensity	l _E	I _F =500 mA		180		mW/sr
		I _{FP} =700 mA*		260		
Beam Angle	2θ _{1/2}	$I_F=100 \text{ mA}$		130		deg.
Rise Time	t r	I _F =500 mA		15		ns
Fall Time	t f	I _F =500 mA		35		ns

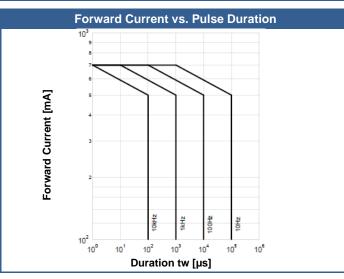
^{*} duty cycle = 1 %, pulse width = 10 μ s

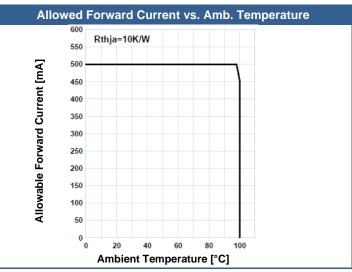
^{**} duty cycle = 1 %, pulse width = 10 μ s

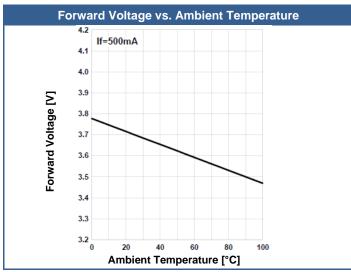
Typical Performance Curves

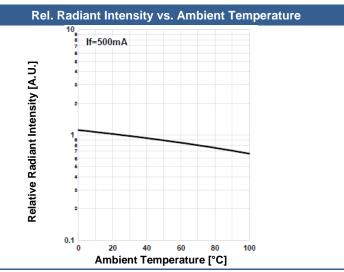




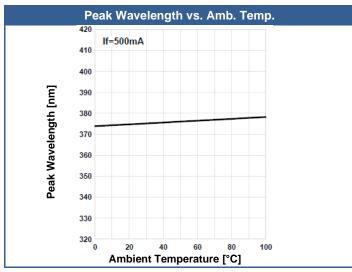


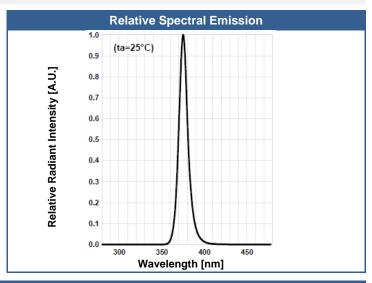


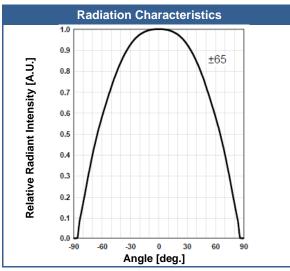


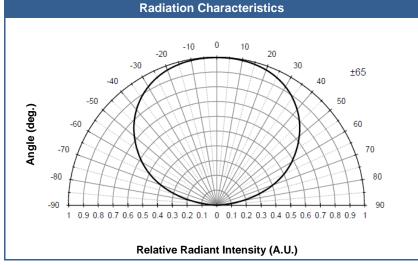


Typical Performance Curves

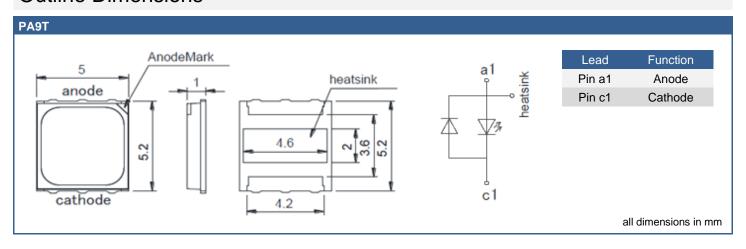








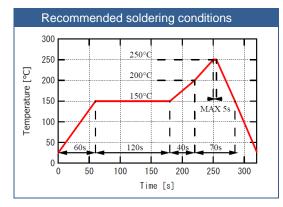
Outline Dimensions

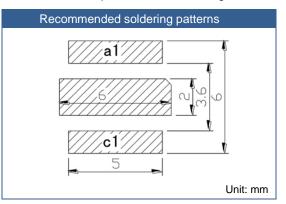


General Notes

Soldering

- · Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- . Do not apply current to the LED until it has cooled down to room temperature after soldering





Cleaning

- . Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended
- DO NOT USE acetone, chloroseen, trichloroethylene, or MKS
- DO NOT USE ultrasonic cleaners

Static Electricity

- LEDs are sensitive to electrostatic discharge (ESD).
- Precautions against ESD must be taken when handling or operating these LEDs
- Surge voltage or electrostatic discharge can result in complete failure of the LED.

Radiation

- During operation these LEDs do emit light, which could be hazardous to skin and eyes, and may cause cancer.
- · Do avoid exposure to the emitted light. Protective glasses if needed
- It is further advised to attach a warning label on products/systems.

Operation

- · Do only operate LEDs with a current source.
- Running these LEDs from a voltage source will result in complete failure of the device.
- Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

Storage

- The maximum shelf life of LEDs in the originally sealed aluminum bag is 12 months.
- Before opening the aluminum bag, please store it at <30 °C, <60 % RH.
- After opening the aluminum bag, please solder the LEDs within 72 hours (floor life) at 5 − 30 °C, <50 % RH.
- Put any unused, remaining LEDs and silica gel back in the same aluminum bag and then vacuum-seal the bag.
- It is recommended to keep the re-sealed bag in a desiccator at <30%RH.

© All Rights Reserved

The above specifications are for reference purpose only and subjected to change without prior notice